

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L3	2	("20020151161").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/07/15 09:25
L4	4	(("5726456") or ("5784129")).PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/07/15 09:26
L5	47	(US-20010002066-\$ or US-20010013652-\$ or US-20020000658-\$ or US-20020070423-\$ or US-20020096764-\$ or US-20020151161-\$ or US-20030052409-\$ or US-20030102551-\$ or US-20030151650-\$ or US-20040000714-\$ or US-20040082183-\$ or US-20040106324-\$ or US-20040108133-\$ or US-20040140561-\$ or US-20040160676-\$ or US-20040178503-\$ or US-20040203235-\$ or US-20040245630-\$ or US-20040266160-\$ or US-20050006788-\$ or US-20050013013-\$ or US-20050047718-\$ or US-20050098775-\$ or US-20050112906-\$ or US-20050127360-\$).did. or (US-5431328-\$ or US-5477087-\$ or US-5790377-\$ or US-5808360-\$ or US-5831832-\$ or US-5929516-\$ or US-6143991-\$ or US-6184582-\$ or US-6445075-\$ or US-6538323-\$ or US-6624071-\$ or US-6734029-\$ or US-6762506-\$ or US-6803658-\$ or US-6818976-\$ or US-6818987-\$ or US-6828677-\$ or US-6841875-\$ or US-6848176-\$ or US-6849944-\$ or US-6894389-\$ or US-6917106-\$). did.	US-PGPUB; USPAT	OR	ON	2005/07/15 09:41

S1	1944	(257/737).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/07/14 14:57
S2	592	(257/781).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/07/14 15:31
S3	121	solder with c5	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/14 15:35
S4	58	"kaneko, tsuyoshi".in.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/14 15:40
S5	1996	lyophilic	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/14 15:41
S6	645	lyophilic and substrate	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/14 15:41
S7	368	lyophilic and substrate and (resin or epoxy)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/15 09:23
S8	55677	(bump or ball) with (epoxy or resin or plastic)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/14 16:11

S9	6687	(bump or ball) with (epoxy or resin or plastic) with layer	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/14 16:25
S10	1618	(bump or ball) with (epoxy or resin or plastic) with layer and thermoset\$4	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/14 16:31
S11	2867	((bump) with (epoxy or resin or plastic)) and "flip chip"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/14 16:33
S12	1522	((bump) with (epoxy or resin or plastic)) and "flip chip" and (cur\$3 or thermoset\$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/14 16:35
S13	132	((bump) with (epoxy or resin or plastic)) and "flip chip" and (thermoset\$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/14 16:35
S14	47	("4597177"   "5207887"   "5346857"   "5431328"   "5477087"   "5642261").PN. OR ("5790377").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/07/14 16:38